



Material Composition Sheet

Product: GS1574ACNE3
 Package Type: QFN-16 Pin
 Manufacturer: Gennum Corporation

Date: 18-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Die		1.77	Al	0.01	0.56	5650
			Si	1.76	99.43	994350
			Sub-total:	1.77	99.99	1000000
Die Attach	8290	0.13	Ag	0.10	76.80	768000
			Amine	0.01	4.00	40000
			Epoxy Resin	0.02	12.00	120000
			Gammabutyrlactate	0.00	3.20	32000
			Metal Oxide	0.01	4.00	40000
			Sub-total:	0.13	100.00	1000000
Internal Pad Plating		0.08	Ag	0.08	100.00	1000000
			Sub-total:	0.08	100.00	1000000
Leadframe	Olin 194FH	17.89	Cu	17.13	95.75	957518
			Mg	0.03	0.16	1677
			Ni	0.60	3.35	33538
			Si	0.13	0.72	7267
			Sub-total:	17.89	99.98	1000000
Marking Ink		0.00		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME G770HT	22.86	Carbon Black	0.07	0.30	3019
			Epoxy Resin	1.07	4.69	46990
			Phenol Resin	0.91	3.99	39989
			Silica Fused	20.80	91.00	910002
			Sub-total:	22.86	99.98	1000000
Terminals Finish		0.55	Sn	0.55	100.00	1000000
			Sub-total:	0.55	100.00	1000000
Wires	GL2	0.07	Au	0.07	100.00	1000000
			Sub-total:	0.07	100.00	1000000
Total:		43.34				

GENNUM CORPORATION

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